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## <u>Architectures</u>

Telefonica I+D and Intel sign a Collaboration Agreement under the Terms of which Telefonica I&D will use Intel® Techology to Develop Solutions for the Telecoms Market -Madrid, October 16 2003

KT and Intel to Jointly Develop Next Generation Network Pilot System based on Intel's Modular Communication Platform - Seoul, Korea, Dec 15, 2003

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NTT Joins OSDL World's largest telecommunications company joins Linux consortium to accelerate development of Linux for enterprise datacenters and carrier grade applications Beaverton, OR and Tokyo, February 3, 2004







